

## 4GBJ10005 THRU 4GBJ1010

## **GLASS PASSIVATED BRIDGE RECTIFIER**

Reverse Voltage - 50 to 1000 Volts Forward Current - 10.0 Ampere

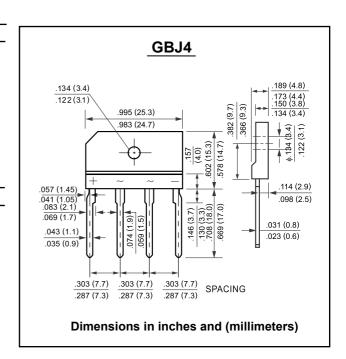
#### **FEATURES**

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capability

#### **MECHANICAL DATA**

- Case: Molded plastic, GBJ
- Terminals: Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any





#### Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	4GBJ 10005	4GBJ 1001	4GBJ 1002	4GBJ 1004	4GBJ 1006	4GBJ 1008	4GBJ 1010	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VR	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	VR(RMS)	35	70	140	280	420	560	700	V
Average Rectified Output Current @T <sub>C</sub> = 115°C (Note 1)	lo	10							Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	220							А
Forward Voltage per diode @I <sub>F</sub> = 5.0A	VFM	1.1							V
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	lR	10 500							μΑ
Typical Thermal Resistance per leg (Note 2)	$R_{ heta}JA$	26							°C/W
Typical Thermal Resistance per leg (Note 1)	R⊕JC	1.9							°C/W
Operating and Storage Temperature Range	Tj, Tstg	-55 to +150							°C

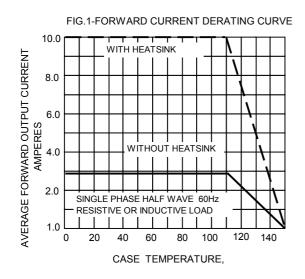
Note: 1. Device mounted on 100 x 100 x 1.6mm thick Al plate heatsink.

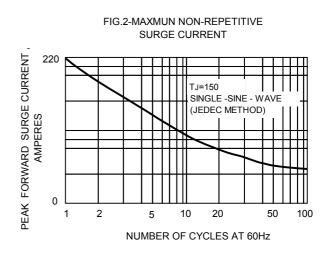
2. Device mounted on P.C.B. without heatsink.

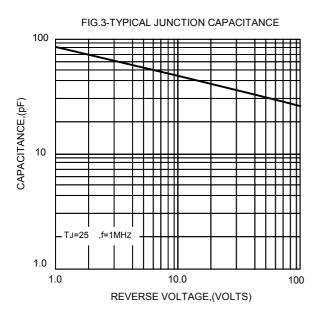


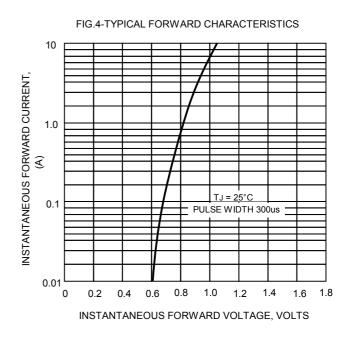
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## **RATINGS AND CHARACTERISTIC CURVES**









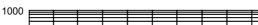


FIG.5-TYPICAL REVERSE CHARACTERISTICS

